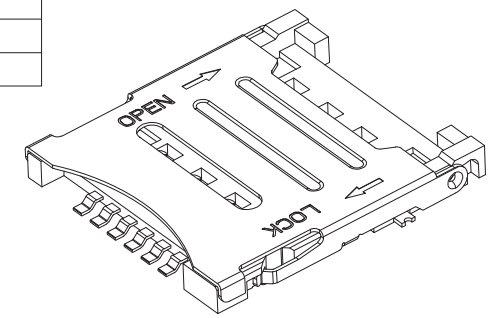


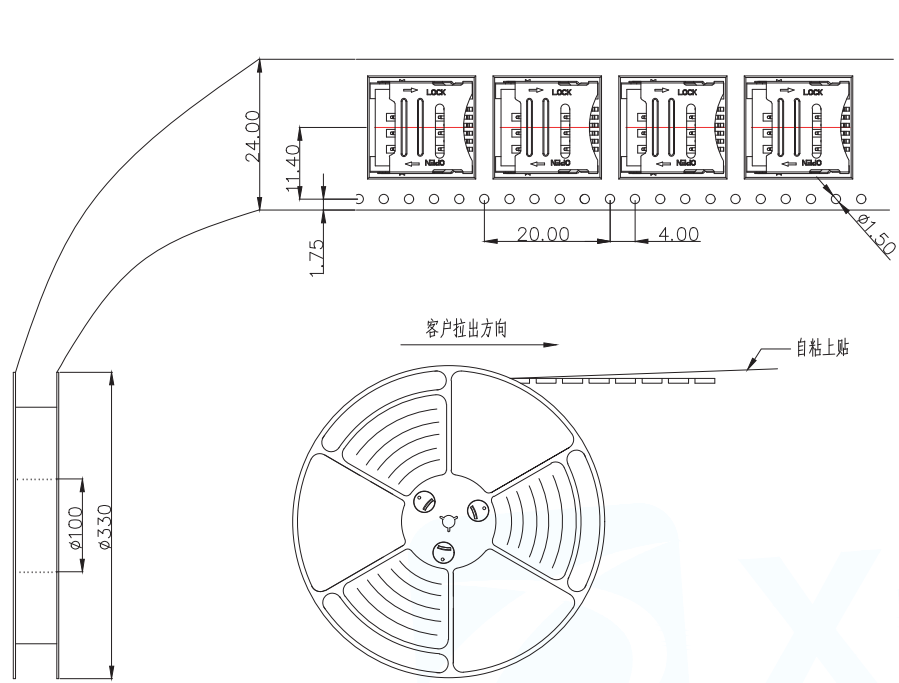
PAD AREA
 KEEP OUT AREA
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

- 一、材质和镀涂:
- 1、胶芯: LCP,UL 94V-0,黑色
 - 2、端子: 磷铜C5210-H,T=0.15, 镍底镀金
 - 3、外壳: 不锈钢SUS304 T=0.2
- 二、技术参数:
- 接触电阻: $100M\Omega$ MAX
 - 绝缘阻抗: $1000M\Omega$ MIN(500DC)
 - 额定电流: 每个接触件1A MAX
 - 额定电压: 30V MAX(DC)
 - 耐压: 500V R.M.S/MIN
 - 使用温度: $-40^{\circ}\text{C} \sim 85^{\circ}\text{C}$
 - 湿度: 90%~95%
 - 寿命: >5000次

MICRO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

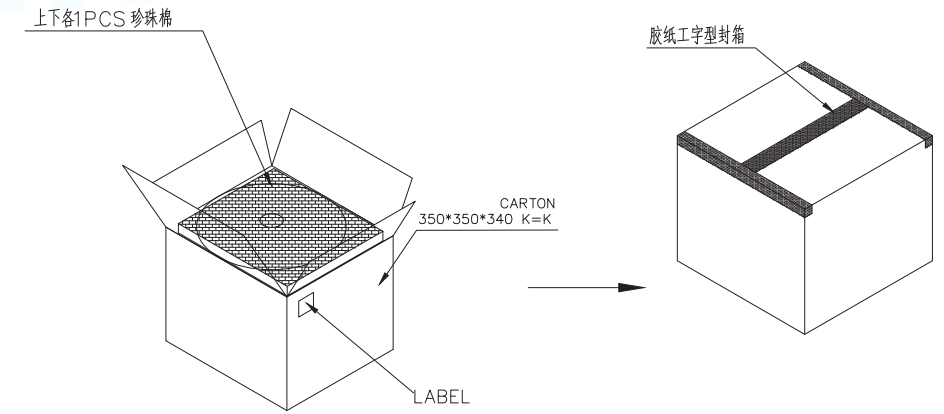
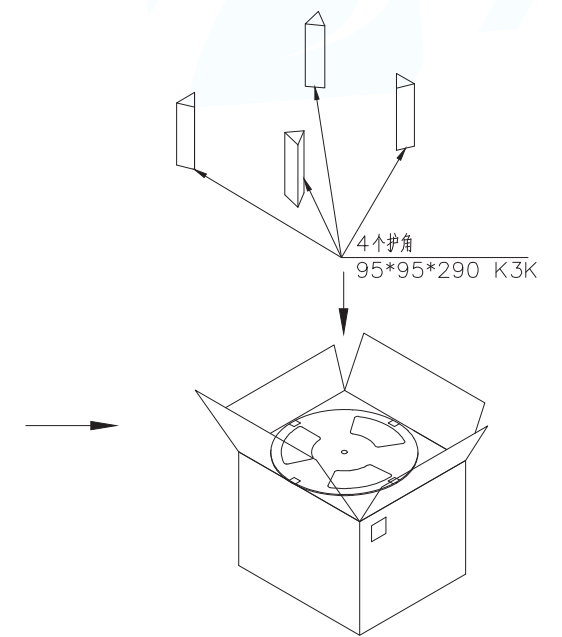


MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: MICRO SIM CARD HINGED 6PIN H1.8 微插式
DECIMALS:	ANGLES:		PAR SMC-216
X.: ± 0.50	X.': $\pm 2^{\circ}$		DWN
X.X: ± 0.30	X.X': $\pm 1^{\circ}$		CHKD
X.XX: ± 0.20		APVD	SCALE: 1:1 UNIT: MM
CUSTOMER COPY		SIZE: A4	SHEET: 1F1 REV: A



NOTES

1. 每卷包装数量: 1200PCS/每卷
2. 卷带包装方式:
3. 每箱包装数量: 12000PCS/箱
4. 纸箱350mm*350mm*440mm(内部尺寸), 材质K=K



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED			TITLE: MICRO SIM CARD HINGED 6PIN H1.8 掀盖式 包装图
			PAR SMC-216
DECIMALS:	ANGLES:		DWN
X.: ±0.50	X.°: ±2'		CHKD
X.X: ±0.30	X.X°: ±1'	APVD	SCALE: 1:1
X.XX: ±0.20		CUSTOMER COPY	UNIT: MM
		SIZE: A4	SHEET: 1F1
			REV: A